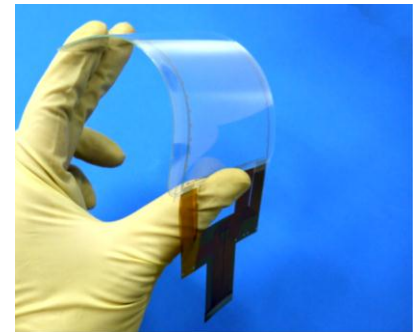


Development of Printed Flex Circuits

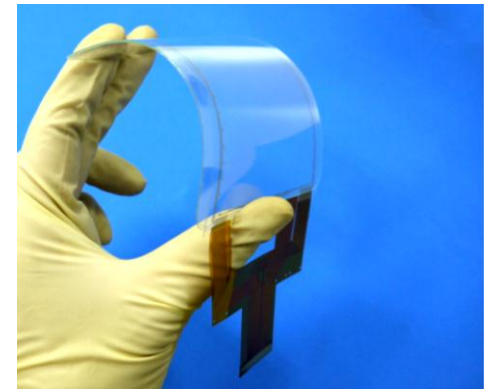


Hirofumi Matsumoto, Ph.D.
Product development planning office
Operating Officer and Division Manager
Nippon Mektron, Ltd.

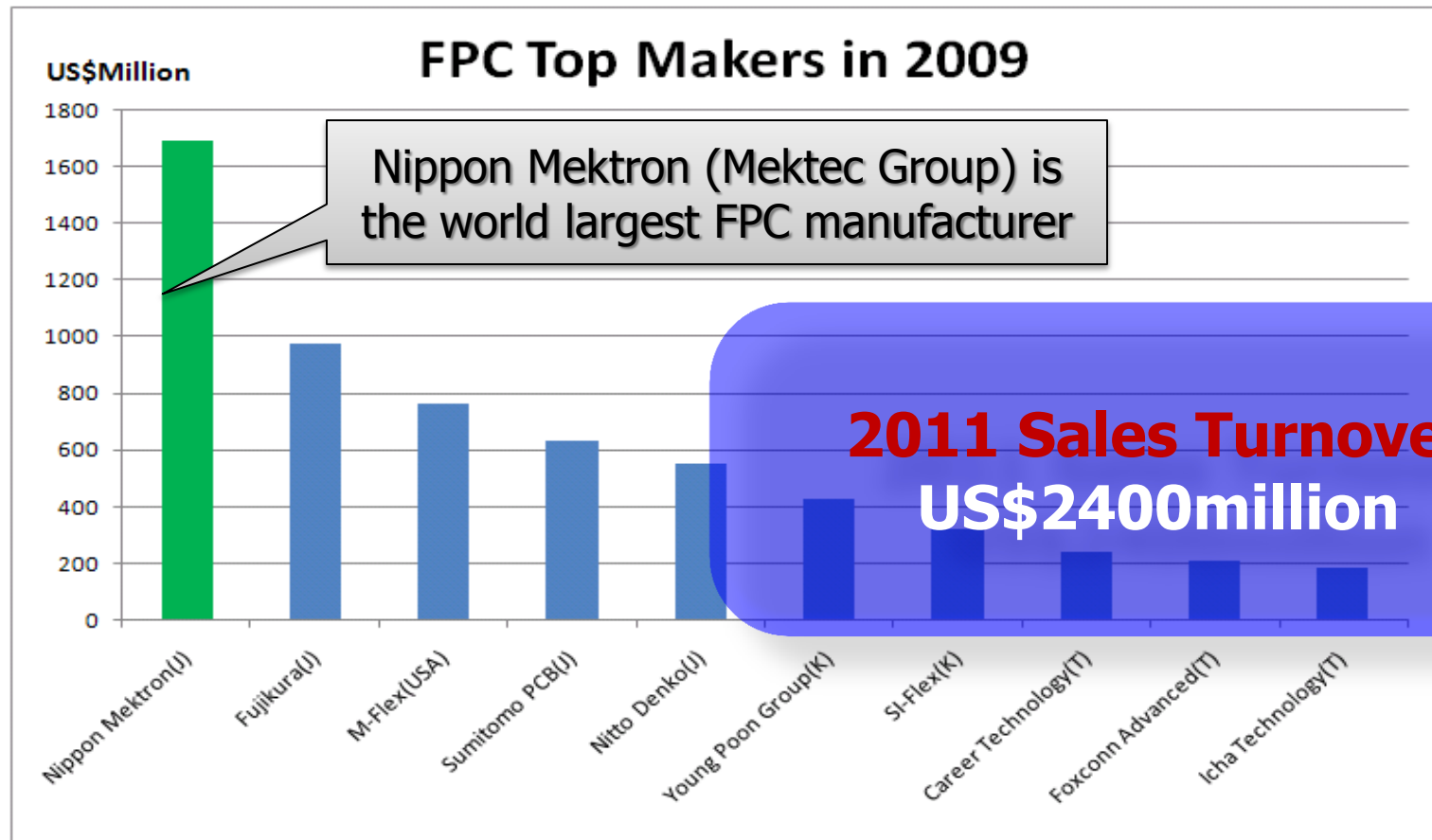


Outline

- Short Company Profile of Nippon Mektron
- Developments of Printed FPCs
 - ❑ PE resist for long FPCs
 - ❑ Flexible Touch Sensor Panel(TSP) application
 - ❑ Single-sided Printed FPCs
 - ❑ Double-sided Printed FPCs
 - ❑ Smart Printed FPCs
- Summary



Sales Turnover of Global FPC Top makers



Global Production Network

13 Factories in 6 Countries

Main Factories



Minami-Ibaraki Plant (Japan)



Kashima Plant (Japan)



Ushiku Okubara Plant (Japan)



Kaohsiung Plant (Taiwan)



Tainan Plant (Taiwan)



Ayutthaya Plant (Thailand)



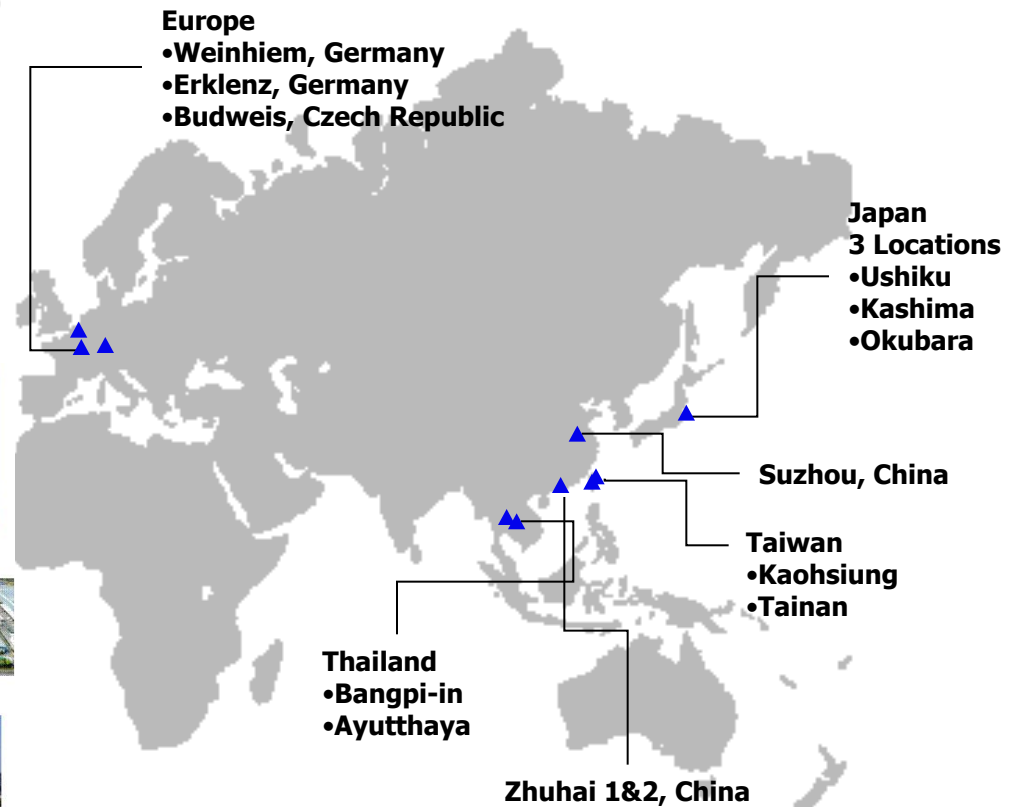
Zhuhai Plant (China)



Longshan Plant (China)



Suzhou Plant (China)

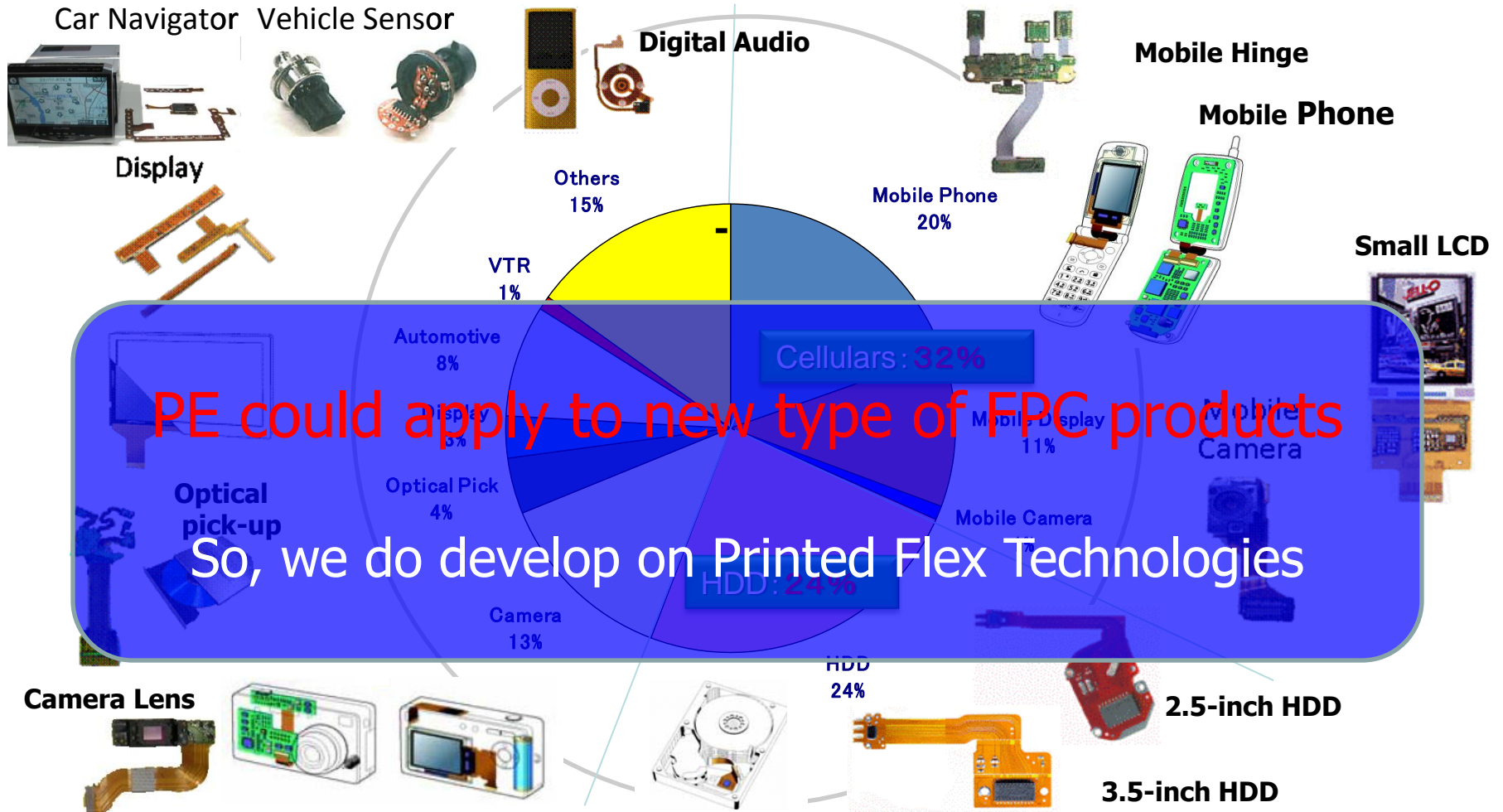


Global Sales Support

25 Sales Locations in 10 Countries



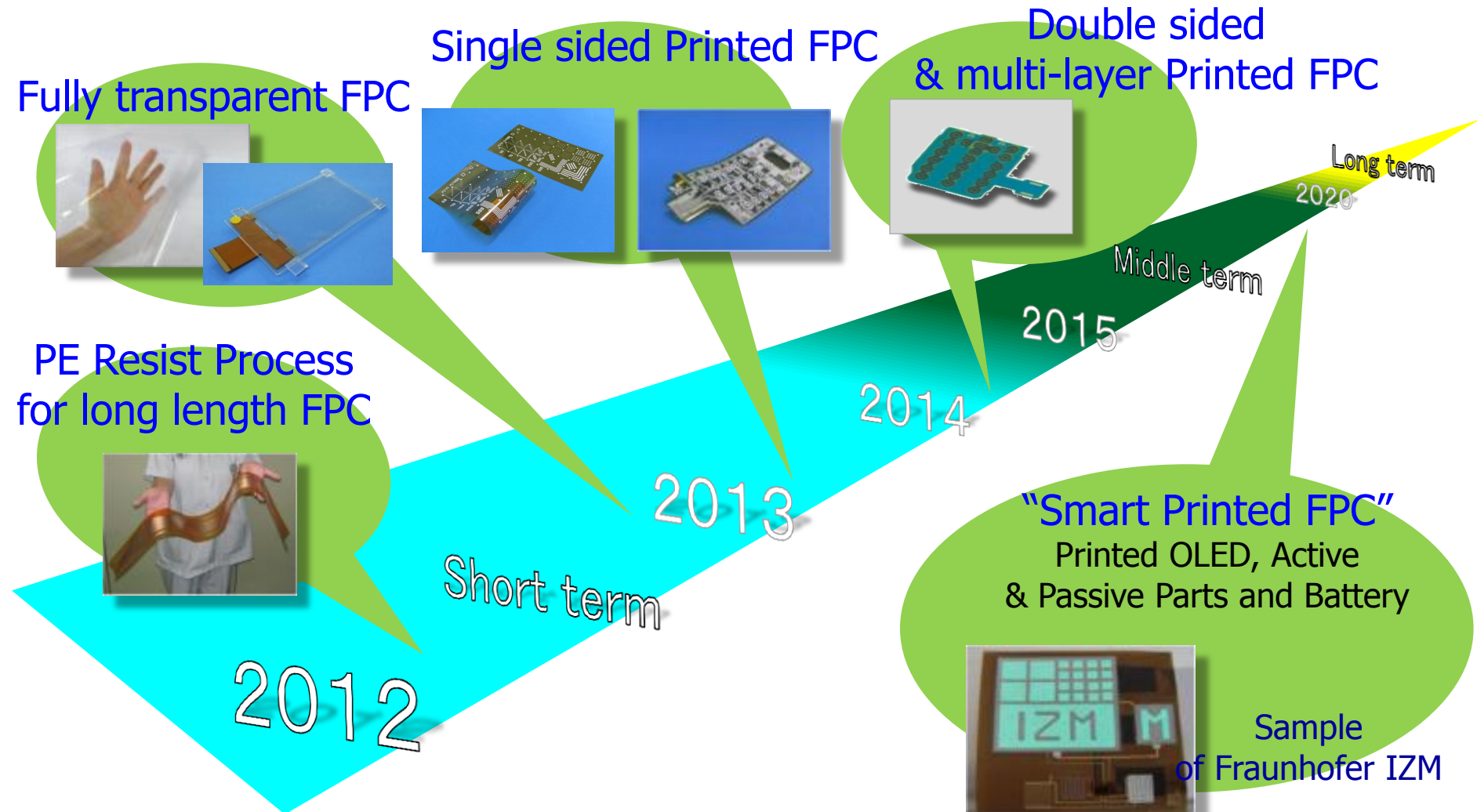
FPC Sales Mix of Mektec Group



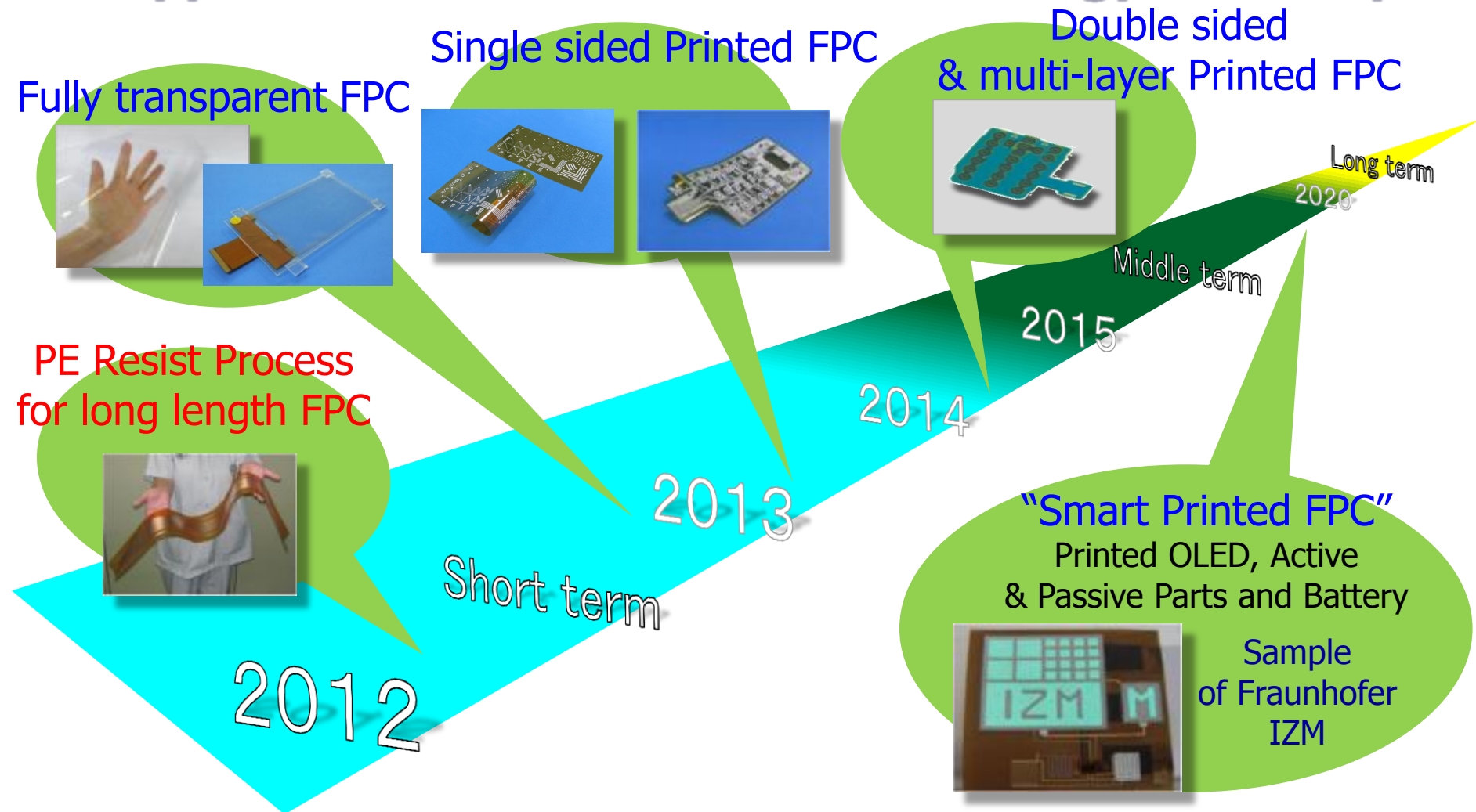
PE could apply to new type of FPC products

So, we do develop on Printed Flex Technologies

Nippon Mektron Printed Flex Technology Roadmap

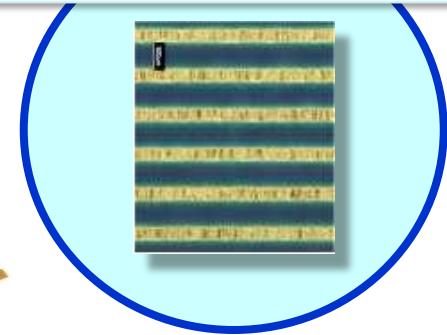
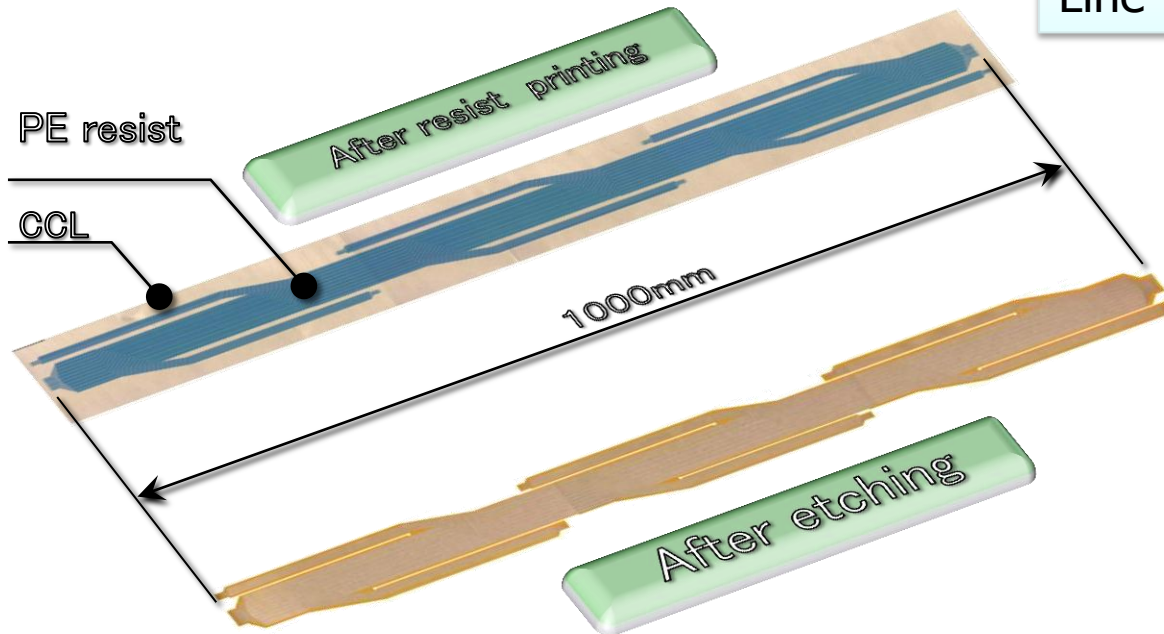


Nippon Mektron Printed Flex Technology Roadmap

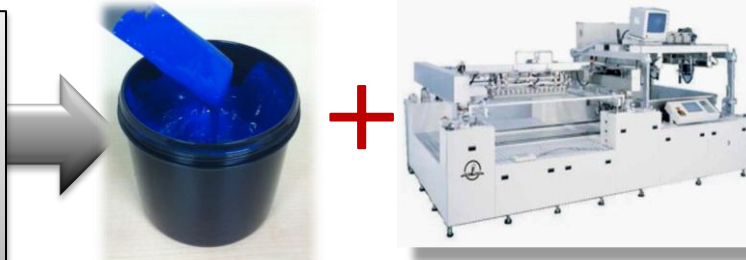


PE Resist Process for long length FPC

Line Width/Space < 100/100 μ m

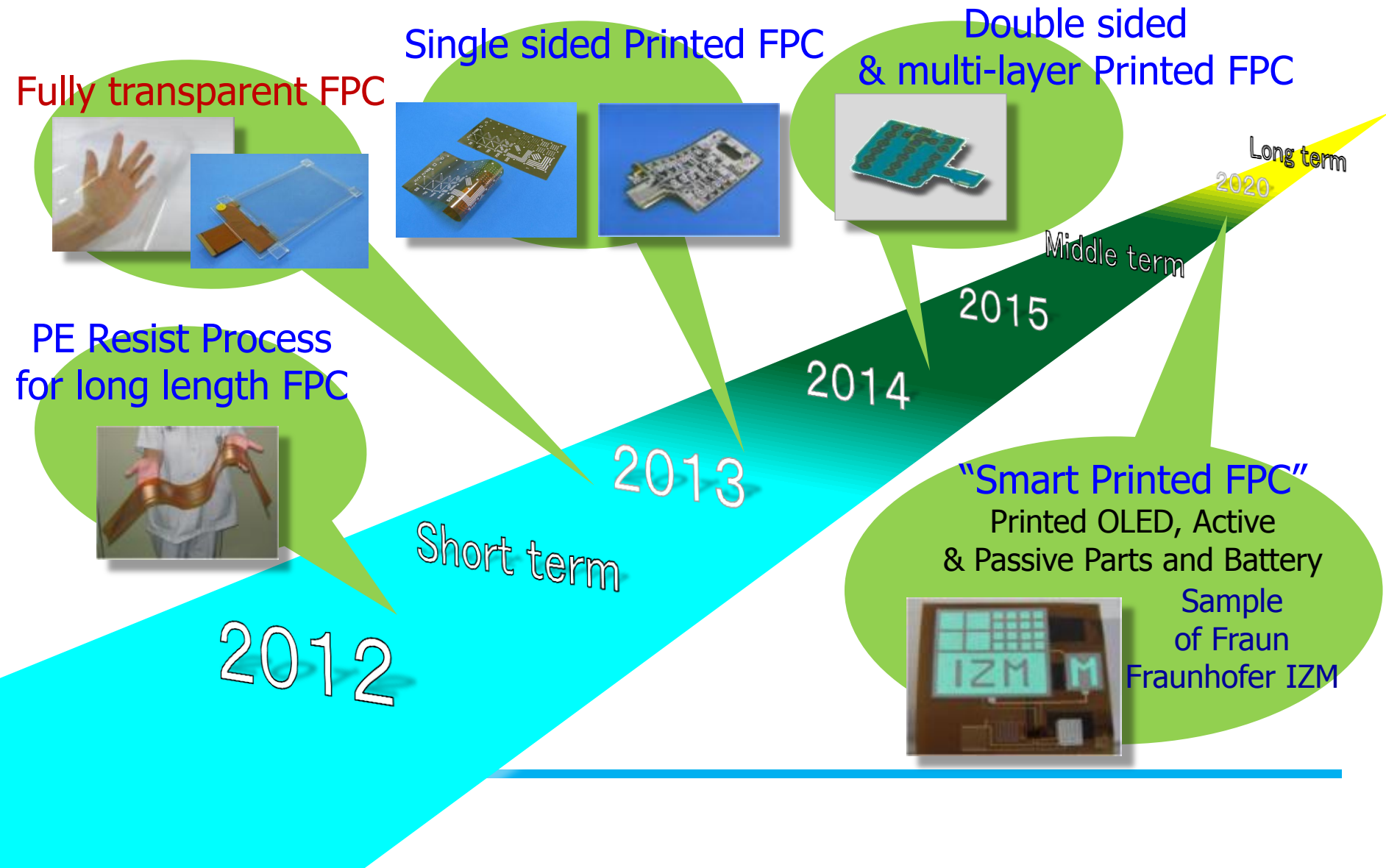


No need to have:
-Dry film lamination
-DF Exposure
-DF development



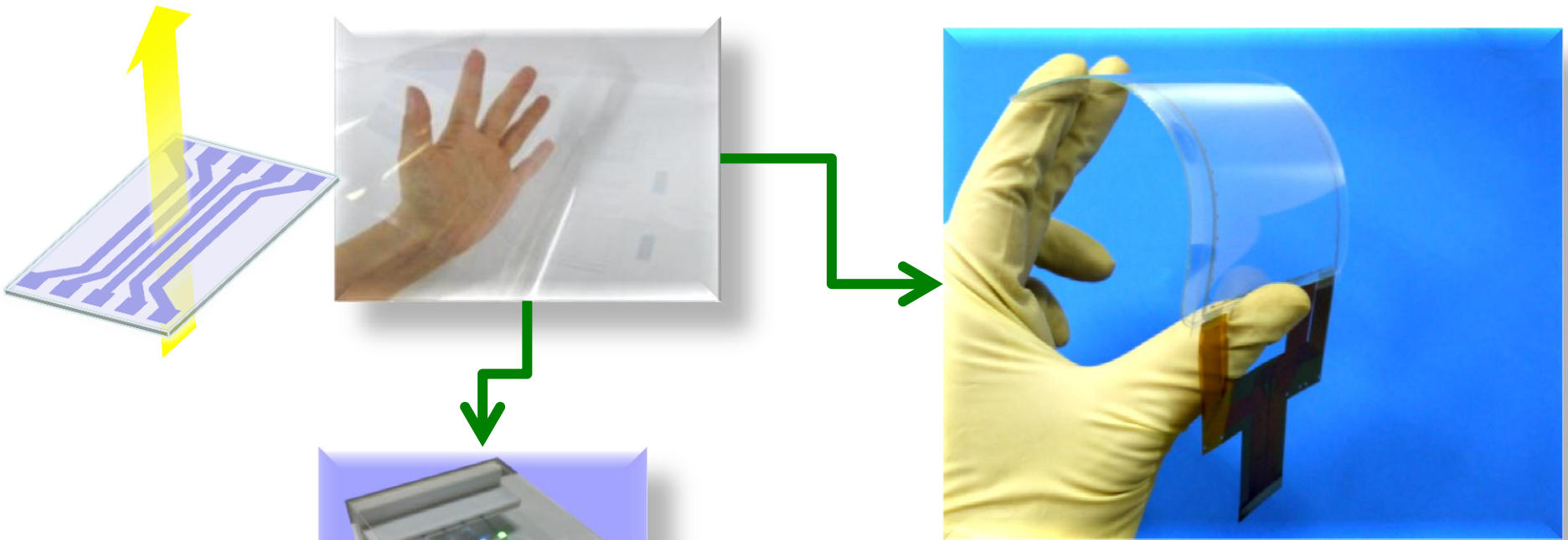
-Low Cost
-Less energy & Material

Nippon Mektron Printed Flex Technology Roadmap



Flexible Touch Sensor Panel(TSP) Development

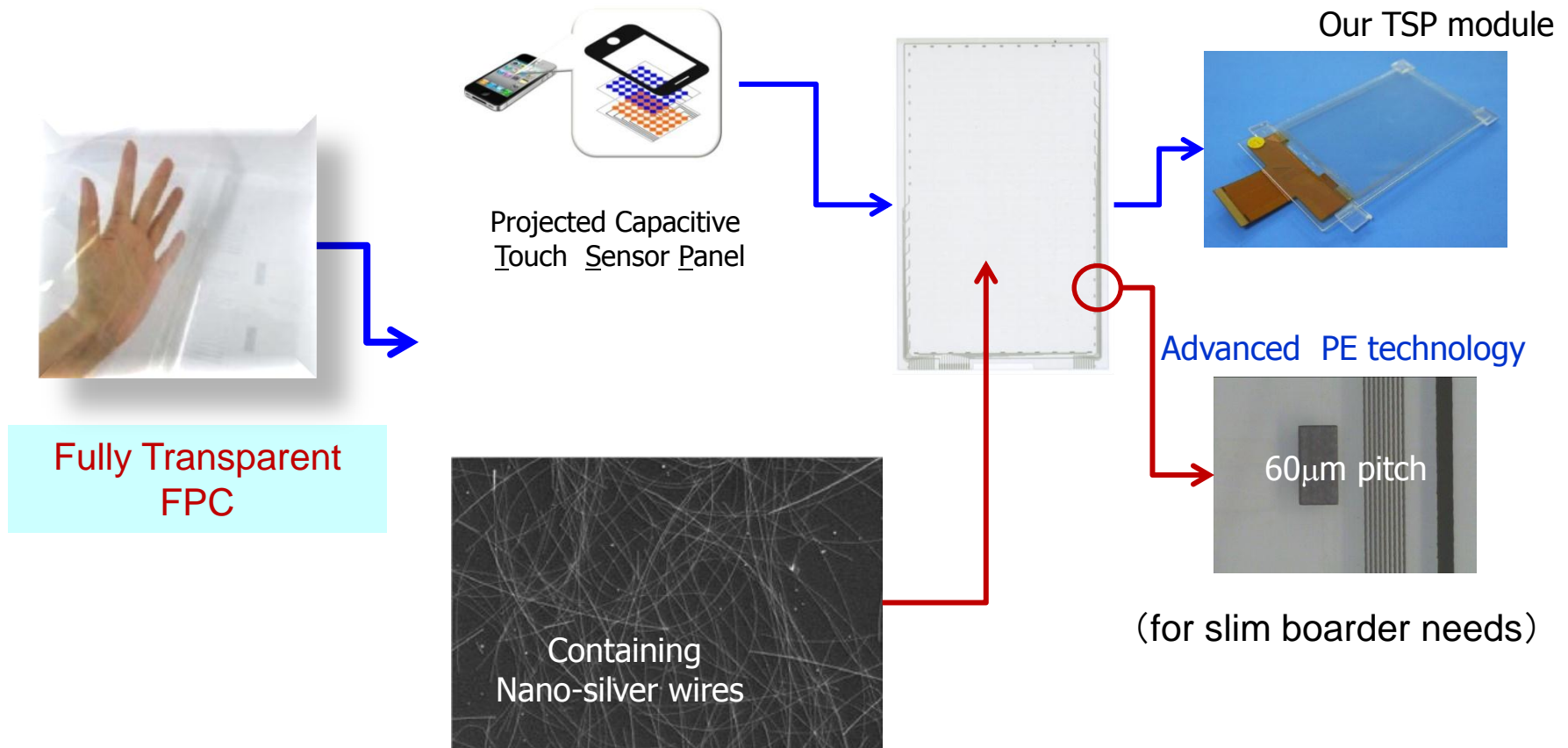
Fully Printed Transparent FPC



LED Transparent FPC

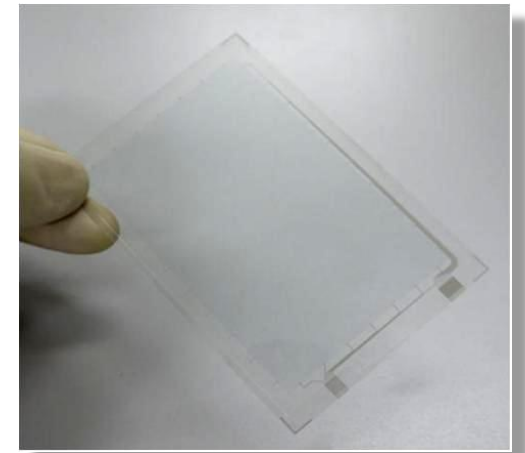
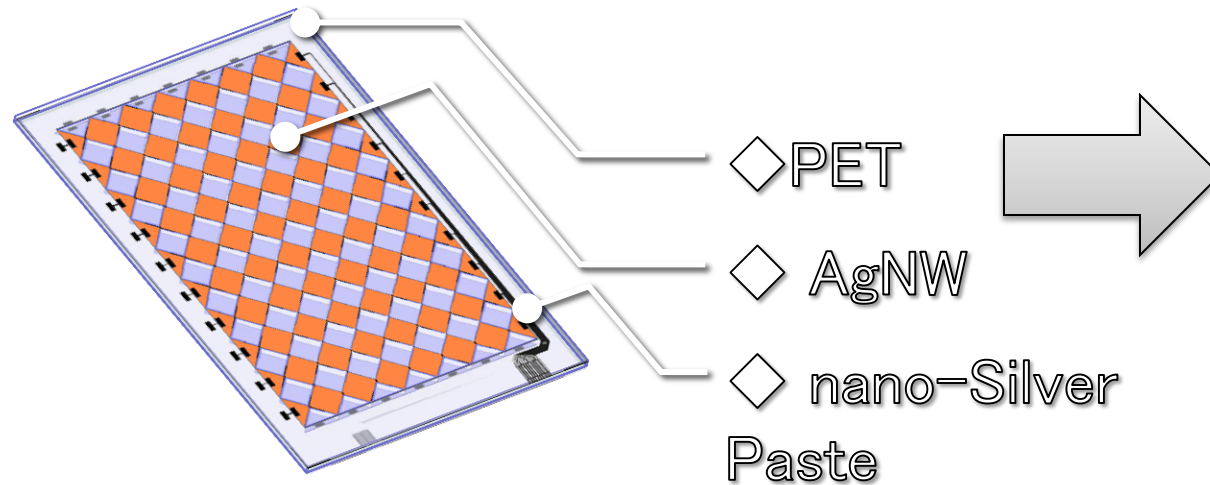
Flexible Printed TSP Module

Touch Sensor Panel Application of Fully Transparent Flex

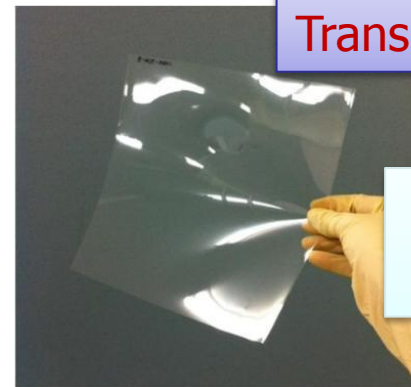


Touch Sensor Panel Application of Fully Transparent Flex

To realize" Projected Capacitive Type"

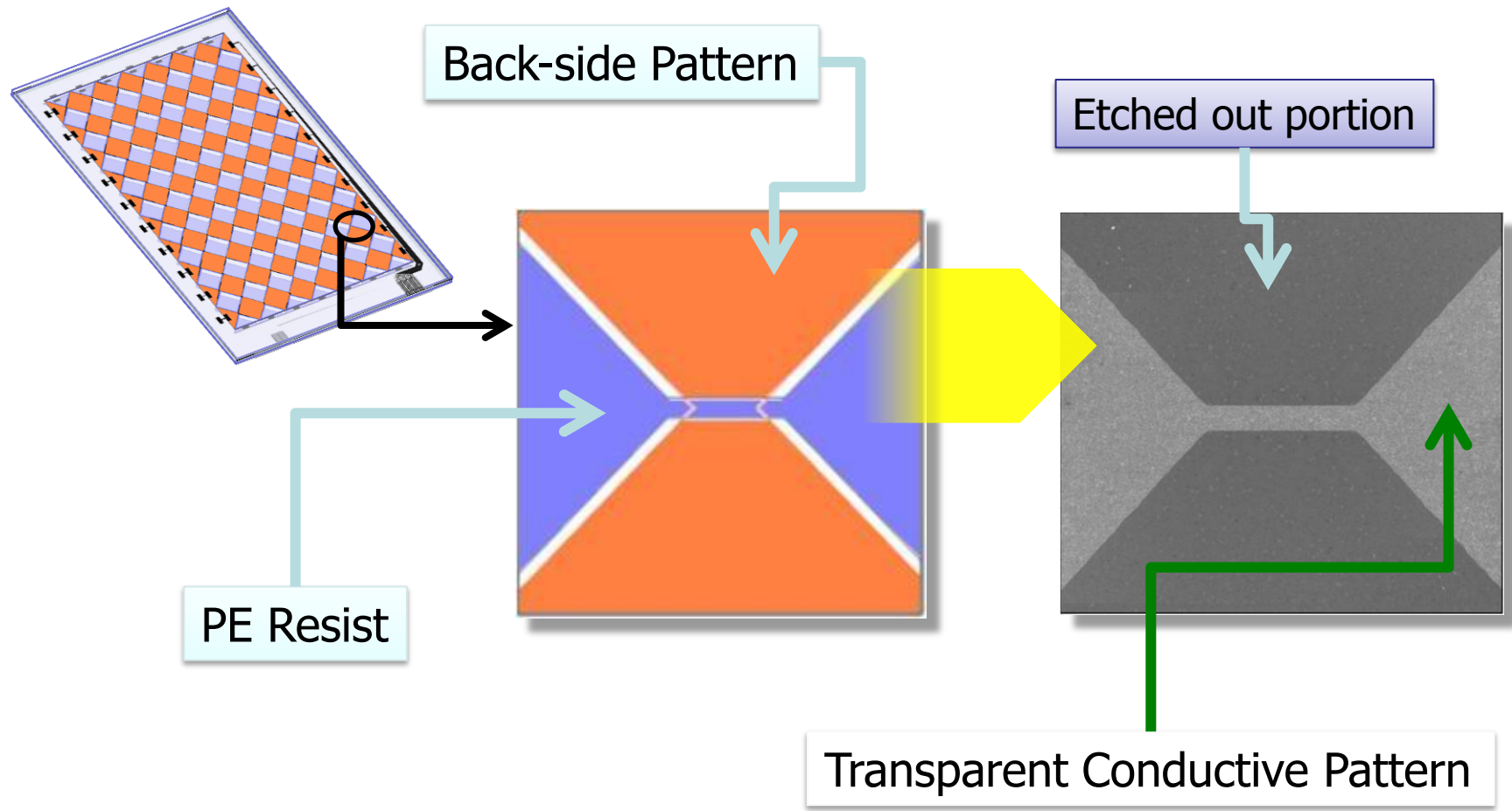


Sheet resistivity < $80 \Omega / \square$
Transparent rate > 90%

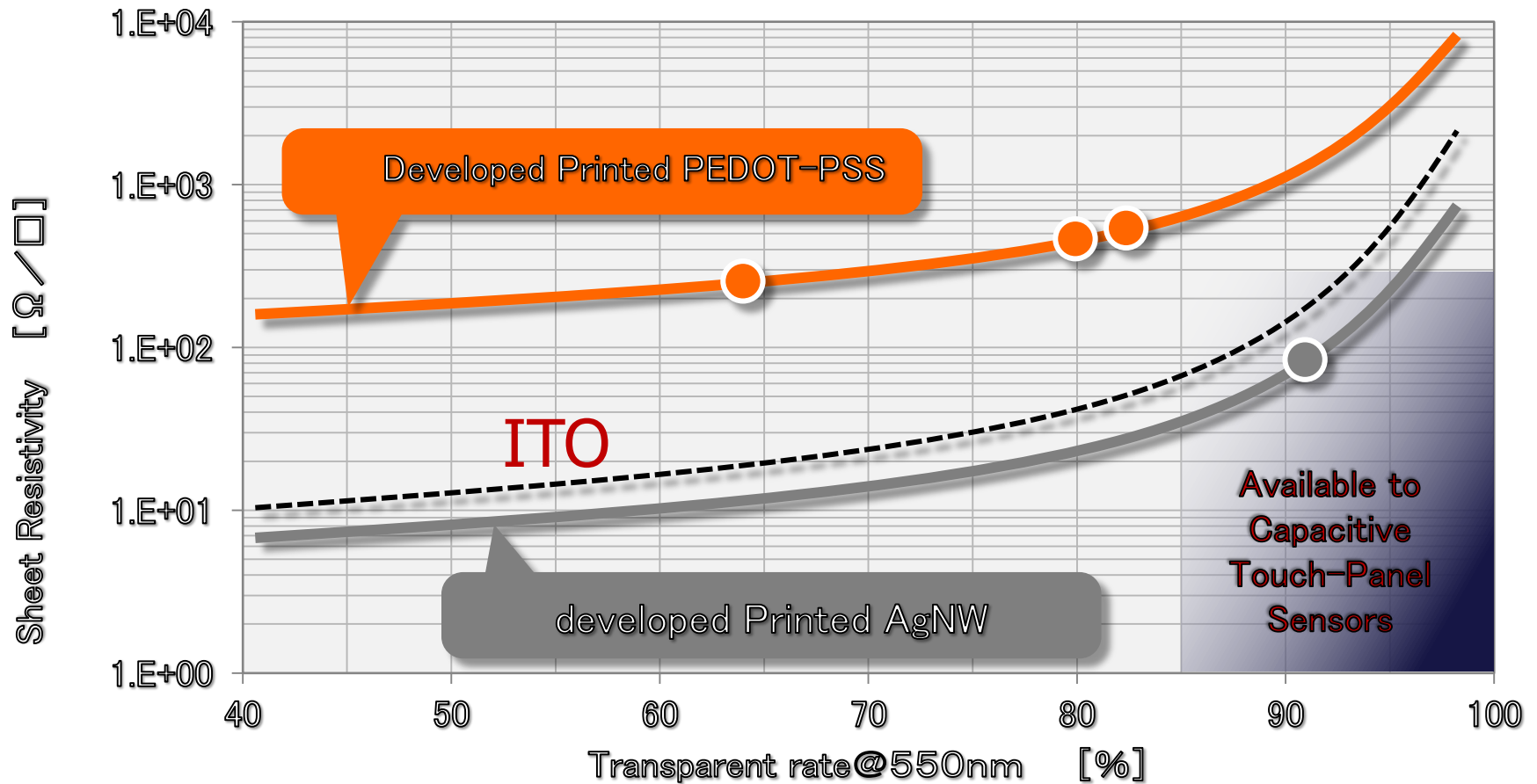


Double-side Printing
AgNW onto PET

AgNW formation by PE

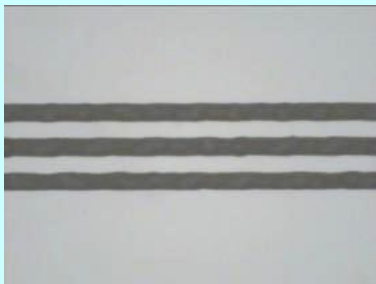


Sheet Resistivity vs. Transparent Rate

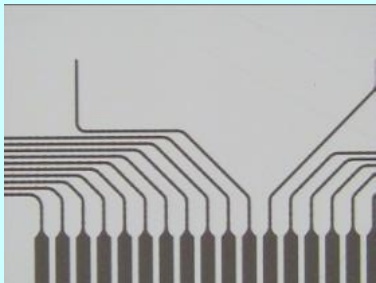


Ag printed wirings

Conventional Ag Printing

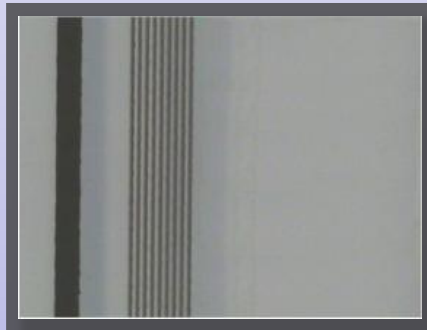


$L/S = 100/100\mu\text{m}$

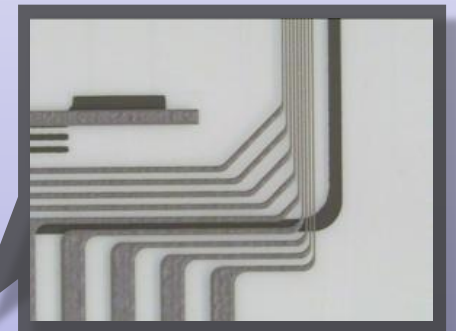
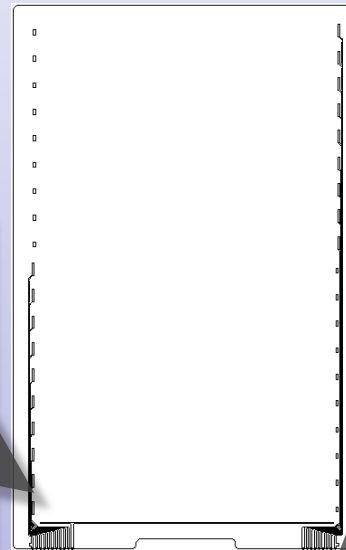


Pitch = $500\mu\text{m}$

Developed "Super Fine Ag Printing"

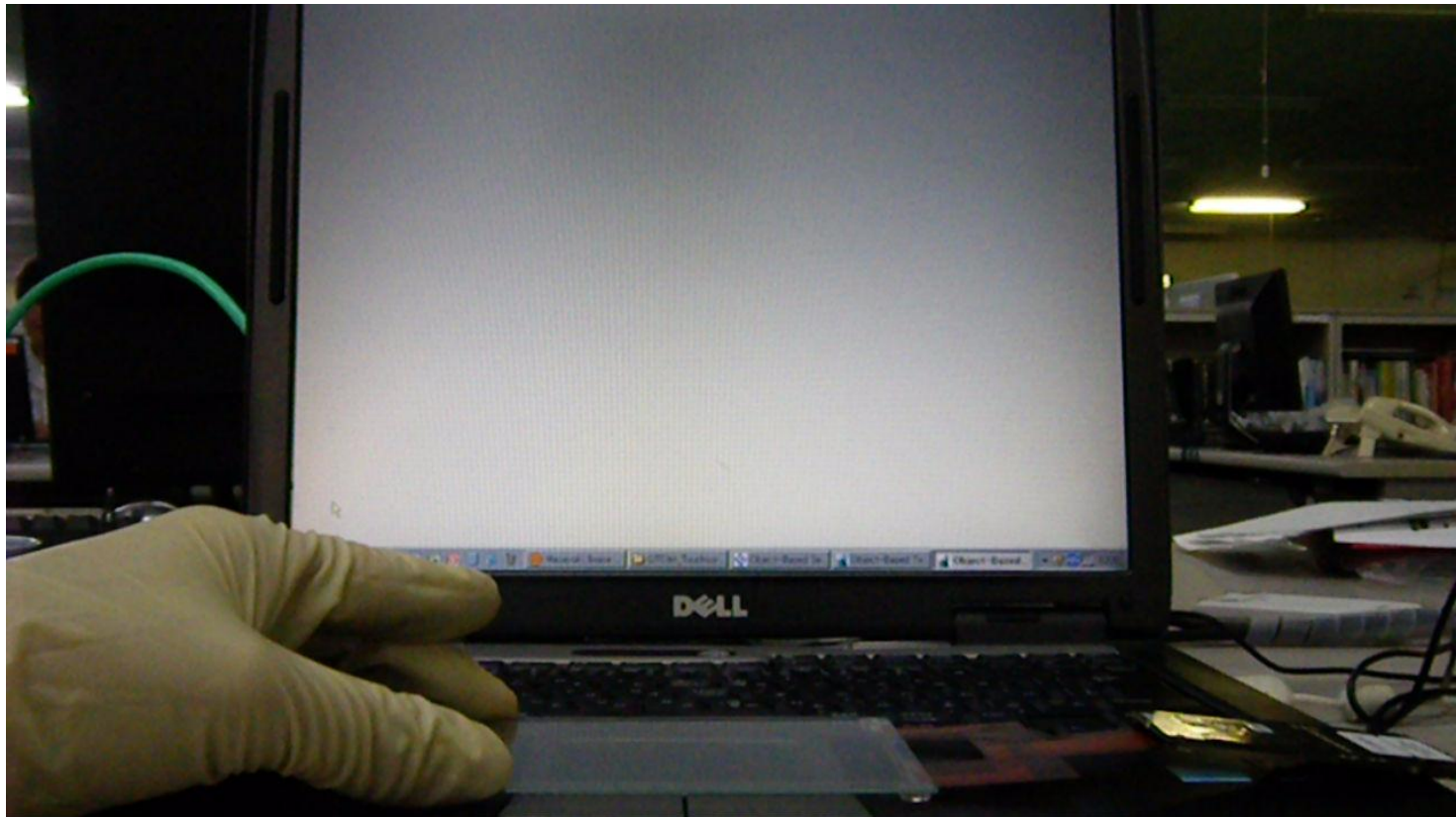


$L/S = 30/30\mu\text{m}$



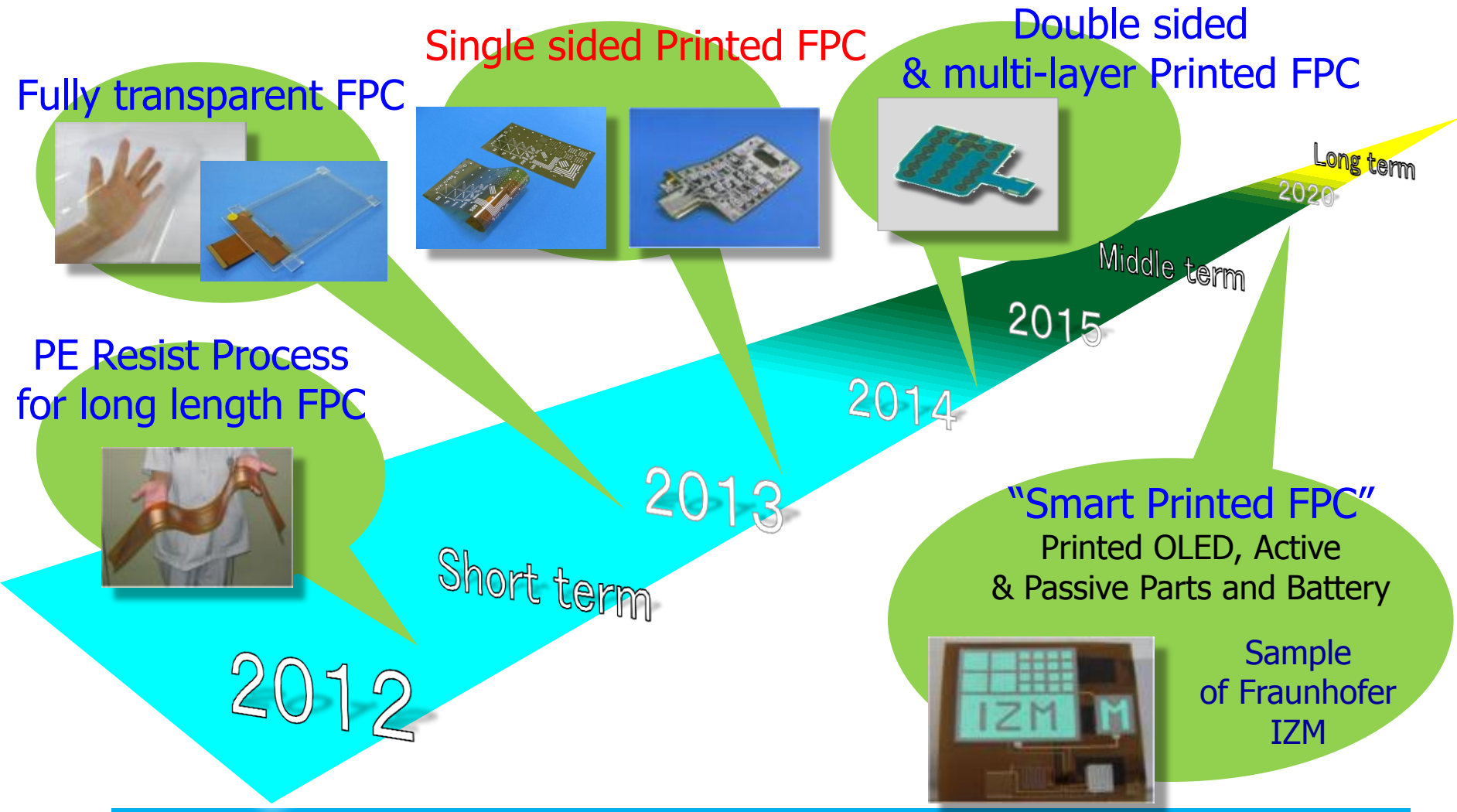
$L/S = 30/30\mu\text{m}$

Projected Capacitive Touch Sensor Panel



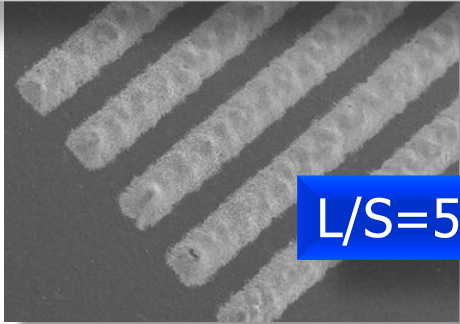
Video demonstration of developed TSP module

Nippon Mektron Printed Flex Technology Roadmap

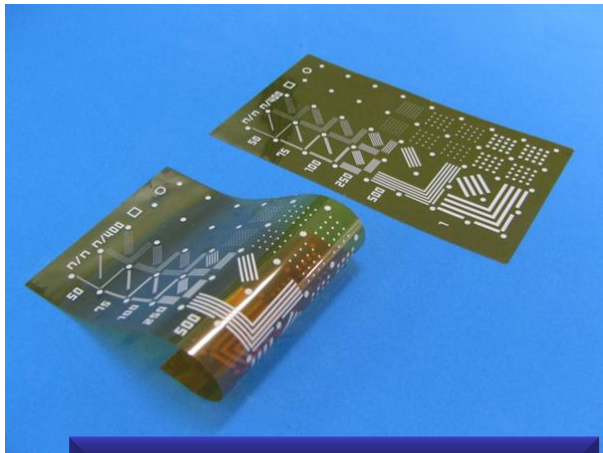


Single-sided Printed FPCs

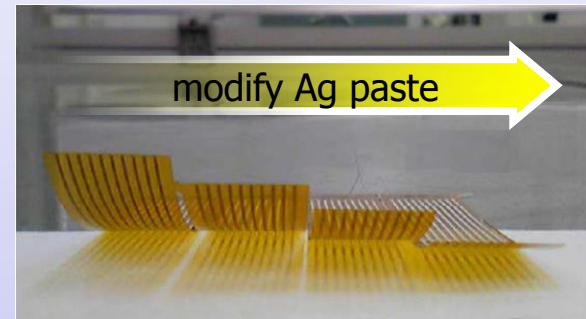
Newly developed Ag paste



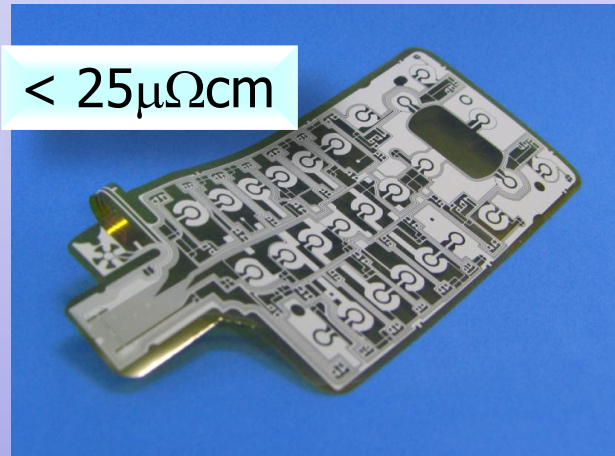
$L/S=50/50\mu\text{m}$



R2R print processing

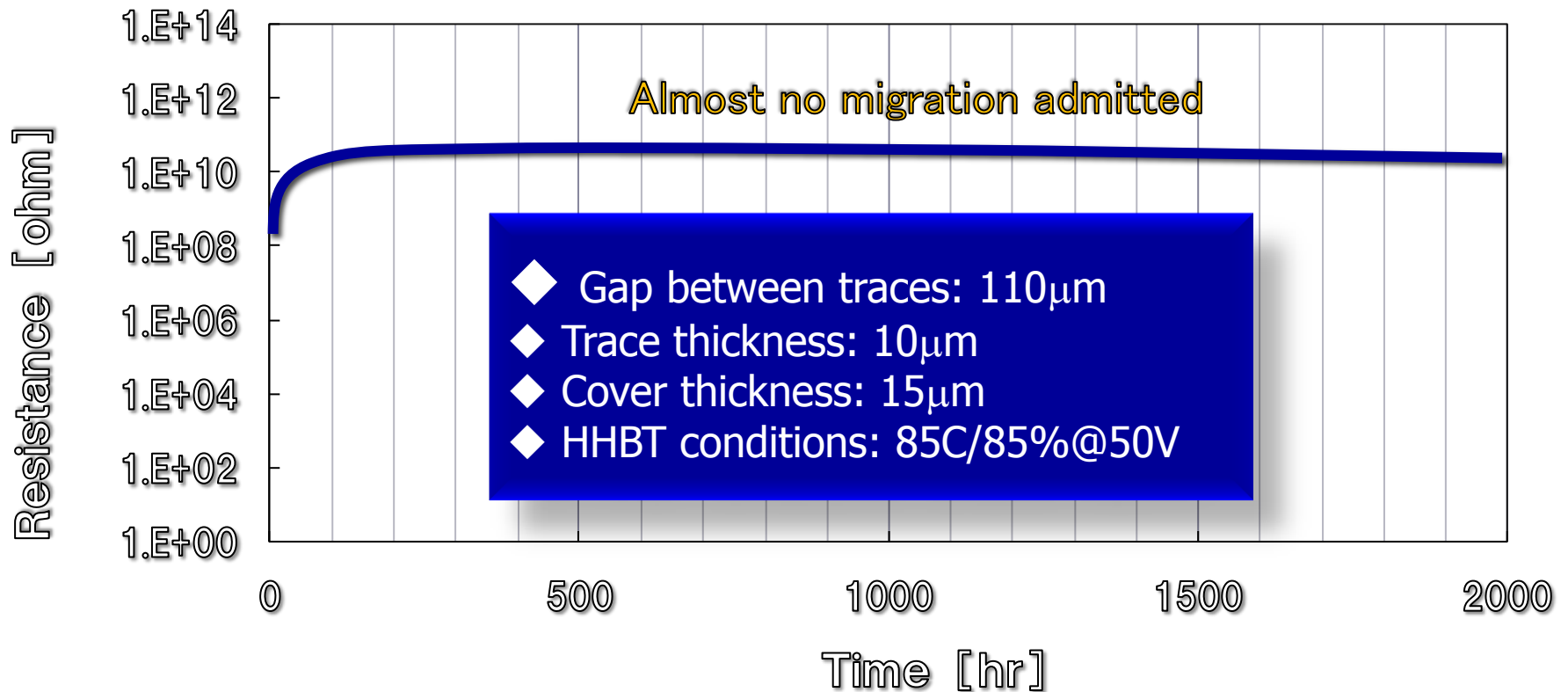


$< 25\mu\Omega\text{cm}$

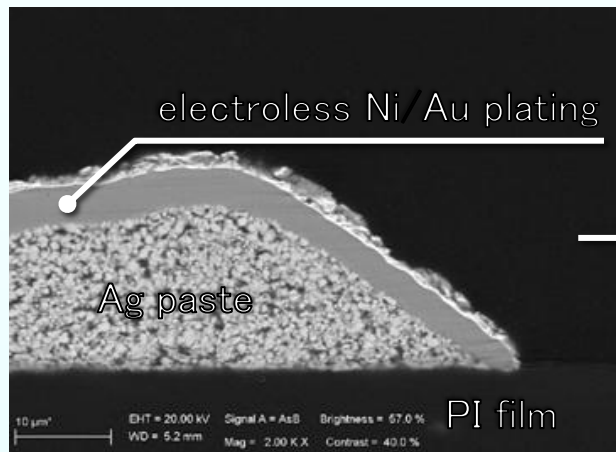


Single-sided Printed FPCs

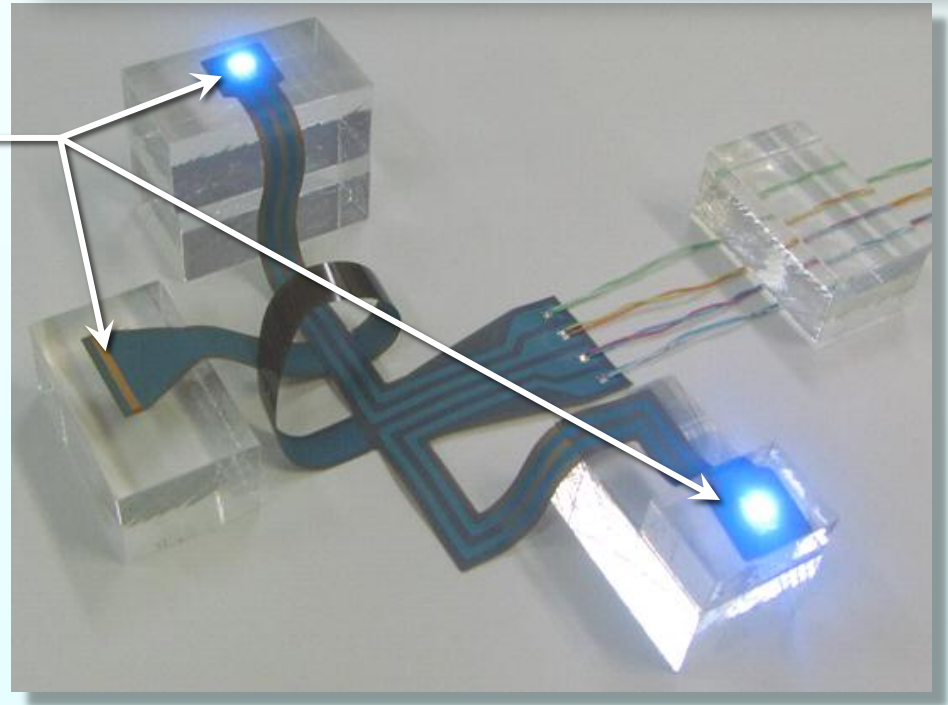
Less or no migration is key issue!!



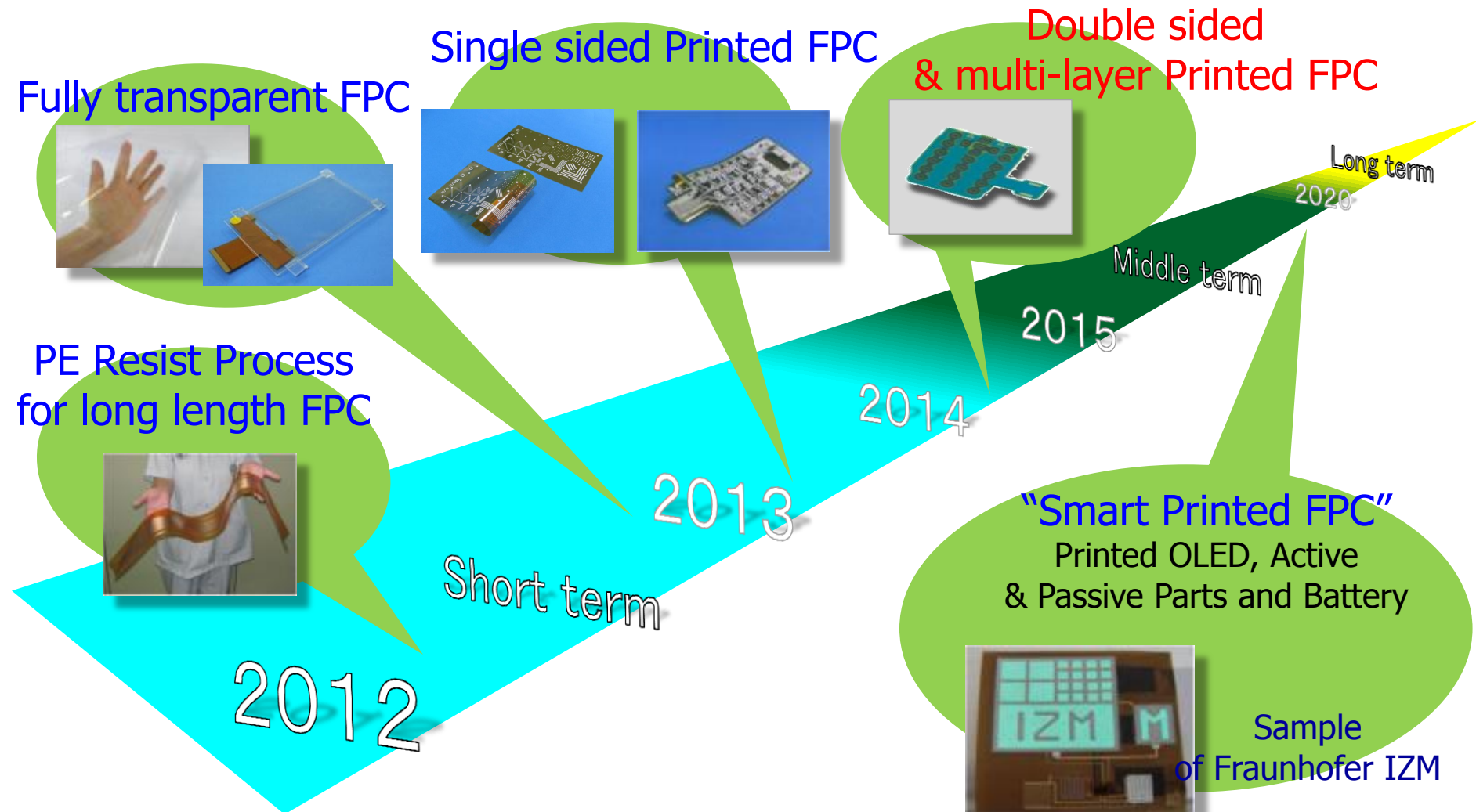
Single-sided Printed FPCs



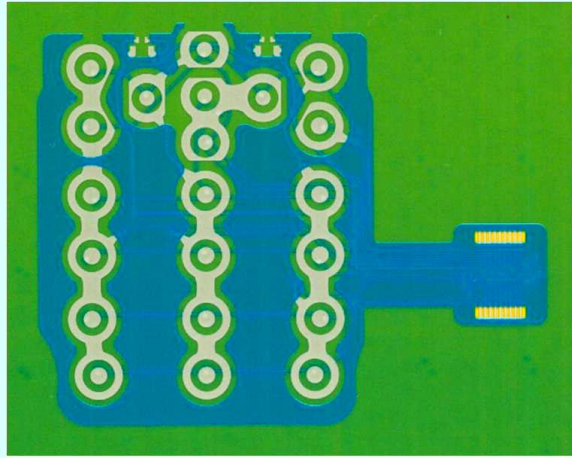
LED assembled SS Printed FPCs



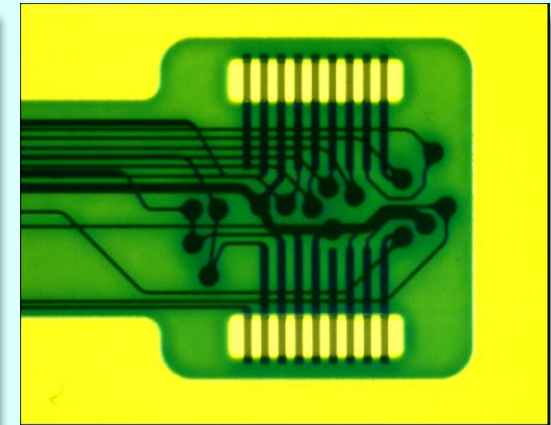
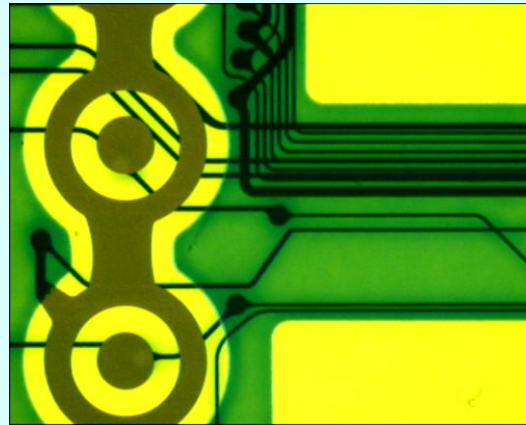
Nippon Mektron Printed Flex Technology Roadmap



Double-sided Printed FPC



Top view of the sample



Second Ag layer

Printed cover

Printed Inter-layer

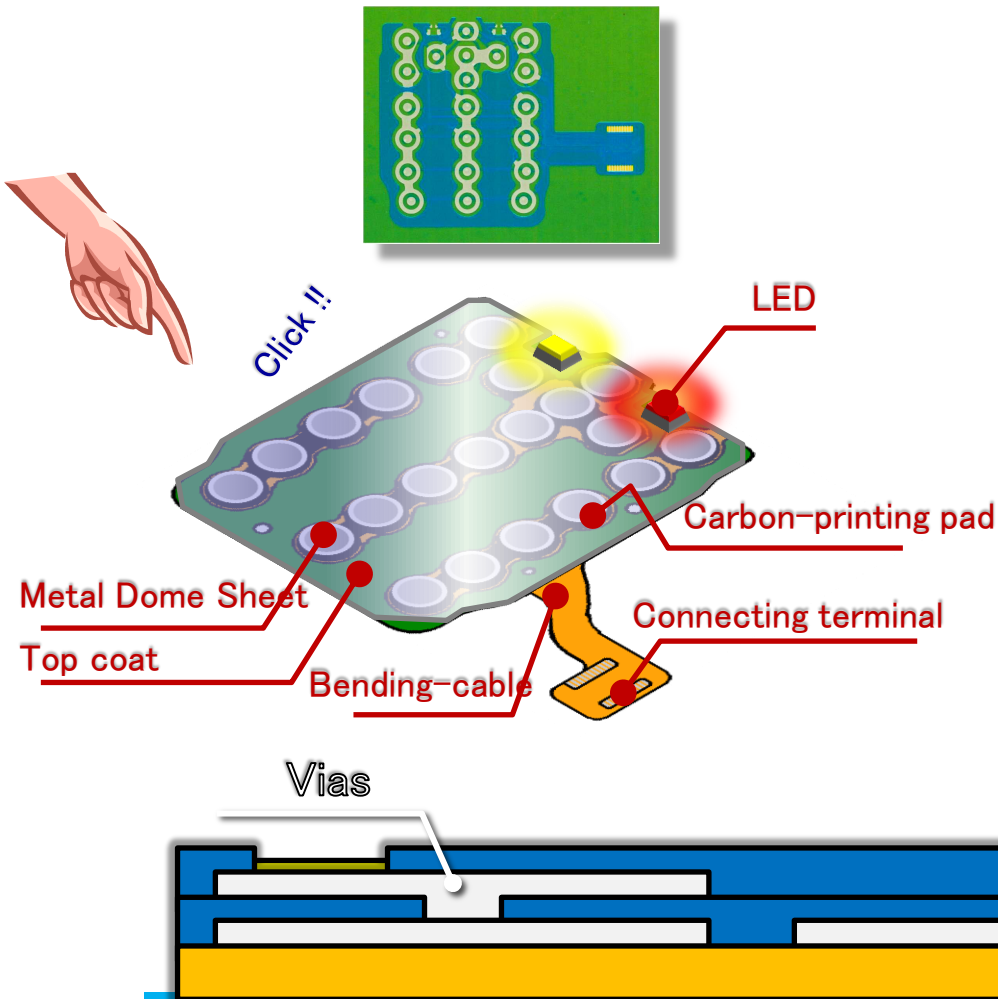
Ni/Au plating

First Ag layer

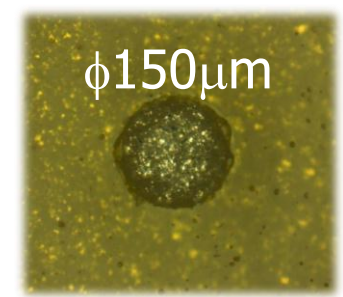
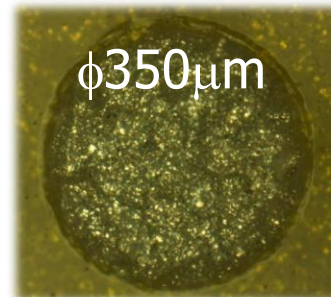
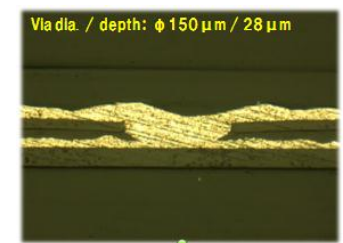
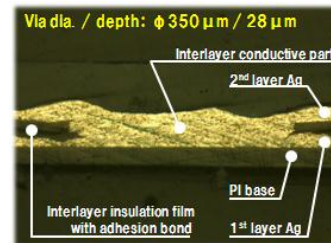
PI film (25 μ m)



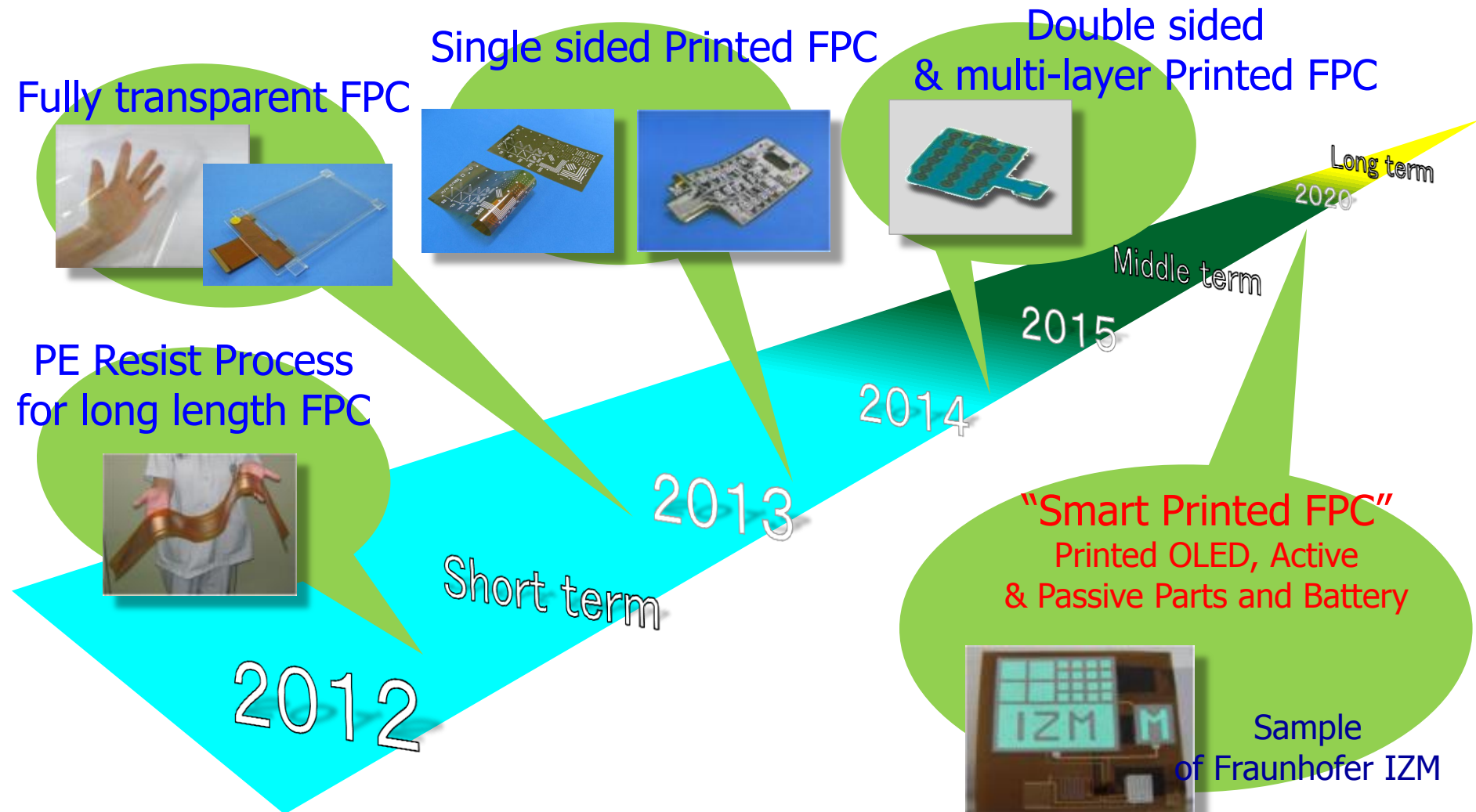
Double-sided Printed FPC



Via formation

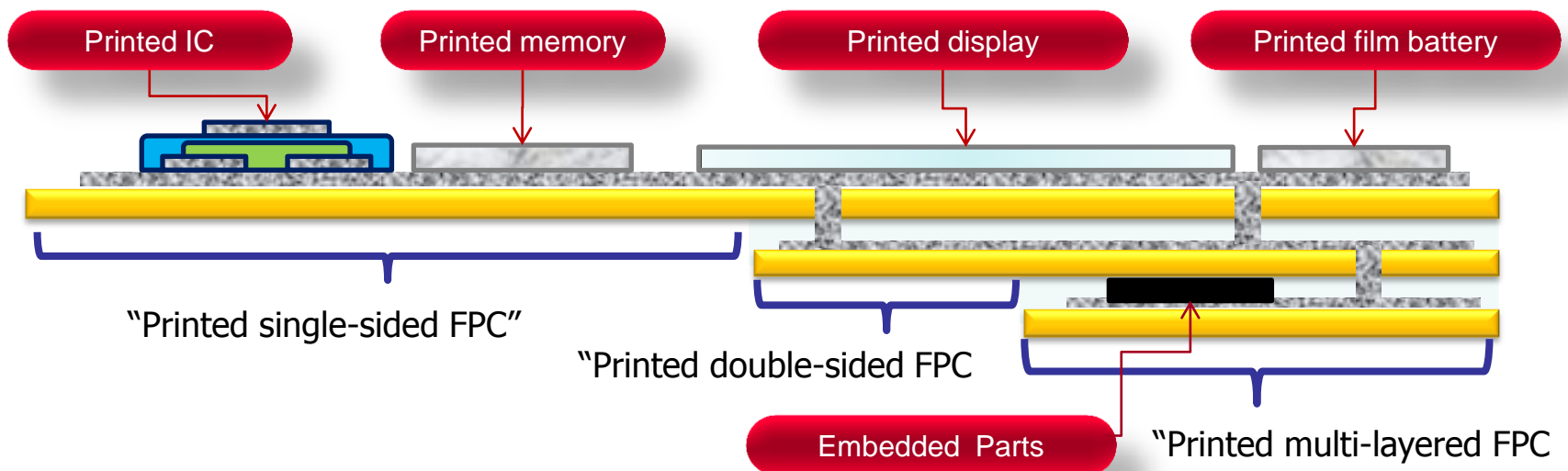


Nippon Mektron Printed Flex Technology Roadmap



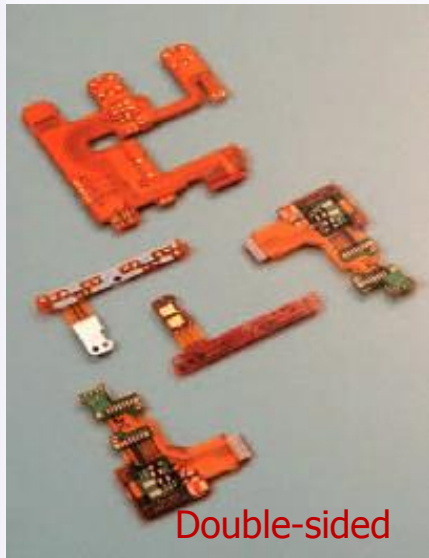
Smart Printed FPCs

Schematic of "Smart Printed FPCs"

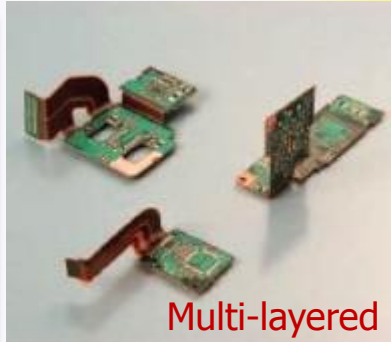


Summary

Current FPC Products



Double-sided



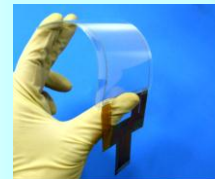
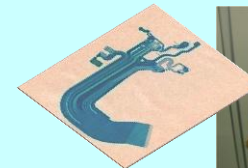
Multi-layered



Single-sided

Photo-lithography products
-Subtractive etching/additive plating-

New FPC Products by “Printed Electronics”



The end

Thank you for your attention

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